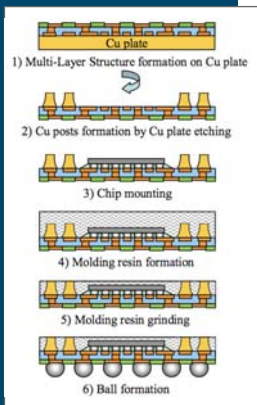
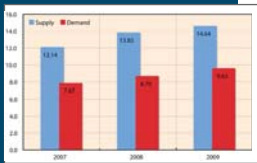
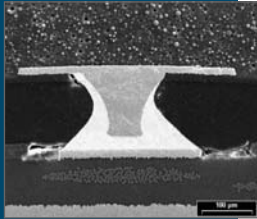


# Advanced Packaging Update: Market and Technology Trends

Vol. 1, 2007



Volume 1 of the Advanced Packaging Update for 2007 features an assessment of laminate substrate capacity including an analysis of supply and demand. An analysis of the flip chip substrate over-capacity situation and the impact on prices is provided. Capacity has been calculated based on a survey of major worldwide suppliers of laminate flip chip substrates. Capacity for wire bond PBGAs and laminate CSPs is also reported. Data from 27 companies making laminate substrates was compiled for the report. A section of the report is devoted to new package-on-package (PoP) developments. Included are developments from Amkor, ASE, IBM Japan, NEC, SPIL, STATSChipPac, Staktek, Tessera, and Texas Instruments. Special sections on IC package contact assembly operations in China and manufacturing operations in India are included. Analysis of popular inexpensive mobile phones made in India reveals the use of advanced packaging, including CSPs, SiPs, and wafer level packages.

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